

CALCE Web Seminar

Hollow Fibers in Printed Wiring Board

Date Dec. 19th

Telecon and Webex start at 11:00am U.S. Eastern (8:00am U. S. Pacific)

Increases in failures due to internal board shorting by conductive filament formation have driven glass and laminate manufacturers to consider screens and qualification tests to assess the hollow fiber concentration of circuit cards. This seminar will describe the hollow fiber problem, its impact on conductive filament formation failures and a hollow fiber screening technique.

About the Presenter: **Dr. Keith Rogers** is the director of the Test Services and Failure Analysis (TSFA) Laboratory at the University of Maryland's CALCE Electronic Products and Systems Center. He has over 10 years of experience working on Material Characterization and Failure Analysis, specializing in the area of electronic packaging. He joined the CALCE Center in 1994 after receiving his B.S. in mechanical engineering from the University of Maryland. His M.S. and Ph.D. degrees, also in mechanical engineering, were completed at the University of Maryland. He has authored and co-authored many articles for various trade magazines and technical journals including *Advanced Materials & Processes*, *Circuit World*, *Circuits Assembly*, *ASM International Practical Failure Analysis*, *Printed Circuit Fabrication*, *IEEE Transactions on Components, Packaging, and Manufacturing Technology*, and *Proceedings of Advanced Technology, Acquisition, Qualification, and Reliability and Symposium for Testing and Failure Analysis*. Dr. Rogers has also made presentations at IEEE, SMTA and IMAPS conferences, in addition to teaching classes on how to perform failure analyses.